IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/525,594 Confirmation No. 7944

Applicant : Ramil Vasquez et al.

Filed : 02/25/2005 TC/A U : 4116

Examiner : MEHTA, MEGHA S.

Docket No. : GB02 0184 US

Customer No. : 65913

Title: Wedge-Bonding of Wires in Electronic Device Manufacture

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

AMENDMENT & RESPONSE

Sir

In response to the non-Final Office Action dated October 18, 2007, please consider the following:

Amendments to the Specification there are no amendments in this paper.

Amendments to the Claims begin on page 2 of this paper.

Remarks/Arguments begin on page 3 of this paper.